

Electronic Patent Application Fee Transmittal

Application Number:	10736618			
Filing Date:	17-Dec-2003			
Title of Invention:	Surface mount chip package			
First Named Inventor/Applicant Name:	Yoshihiro Ohkura			
Filer:	Joseph W. Ragusa/Haydee Cruz			
Attorney Docket Number:	X2007.0147			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1020	1020

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				1810